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Response to Office Action mailed February 7, 2002

PATENT

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TECHNOLOGY CENTER 2800

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Ronald Pasqualini

Appln. No.: 09/164,216 \

Filed: September 30, 1998

For: ESD PROTECTION CIRCUIT UTILIZING
FLOATING LATERAL CLAMP DIODES

Group Art Unit: 2811

Examiner: O. Nadav

RESPONSE TO OFFICE ACTION MAILED
FEBRUARY 7, 2002

CERTIFICATE OF MAILING

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Washington D.C. 20231-9999 on 05-07-02.

Commissioner for Patents
Washington, D.C. 20231

Dated: 05-07-02

By Stephen L. Keag

Dear Sir:

In response to the Official Action mailed February 7, 2002, please amend the above-identified application as follows:

In the Claims

The claims have been amended to read as follows:

SUB G1
F1

15. (Fourth Amendment) A semiconductor chip having a substrate of a first conductivity type, the chip comprising:
- a plurality of pads;
 - an electrostatic discharge (ESD) negative ring;
 - a plurality of ESD positive lines, the plurality of positive lines not being electrically connected to each other, none of the positive lines being connected to a pad;
 - a plurality of ESD switches connected to the ESD positive lines and the ESD negative ring so that each positive line is connected to the negative ring via an ESD switch;
 - a plurality of first diodes connected to the pads so that each first diode is connected to a pad and the negative ring; and

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Atty. Docket No. 072219-0274869 (P03921-C2)